

DS64EV100 Programmable Single Equalizer

Check for Samples: [DS64EV100](#)

FEATURES

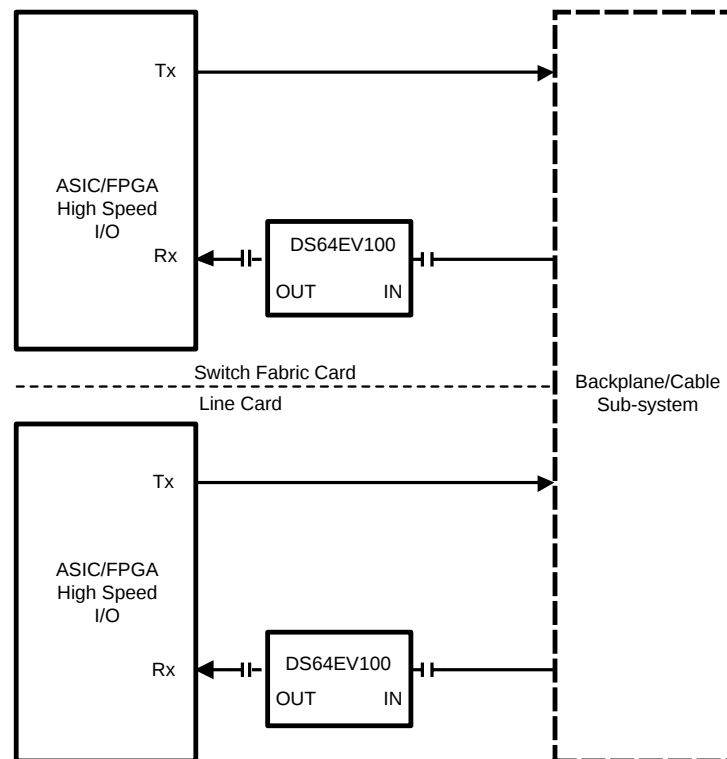
- Equalizes up to 24 dB loss at 10 Gbps
- Equalizes up to 22 dB loss at 6.4 Gbps
- 8 levels of programmable equalization
- Operates up to 10 Gbps with 30" FR4 traces
- Operates up to 6.4 Gbps with 40" FR4 traces
- 0.175 UI residual deterministic jitter at 6.4 Gbps with 40" FR4 traces
- Single 2.5V or 3.3V power supply
- Supports AC or DC-Coupling with wide input common-mode
- Low power consumption: 100 mW Typ at 2.5V
- Small 3 mm x 4 mm 14-pin WSON package
- > 8 kV HBM ESD Rating
- -40 to 85°C operating temperature range

DESCRIPTION

The DS64EV100 programmable equalizer provides compensation for transmission medium losses and reduces the medium-induced deterministic jitter for NRZ data channel. The DS64EV100 is optimized for operation up to 10 Gbps for both cables and FR4 traces. The equalizer channel has eight levels of input equalization that can be programmed by three control pins.

The equalizer supports both AC and DC-coupled data paths for long run length data patterns such as PRBS-31, and balanced codes such as 8b/10b. The device uses differential current-mode logic (CML) inputs and outputs. The DS64EV100 is available in a 3 mm x 4 mm 14-pin leadless WSON package. Power is supplied from either a 2.5V or 3.3V supply.

Simplified Application Diagram



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Pin Diagram

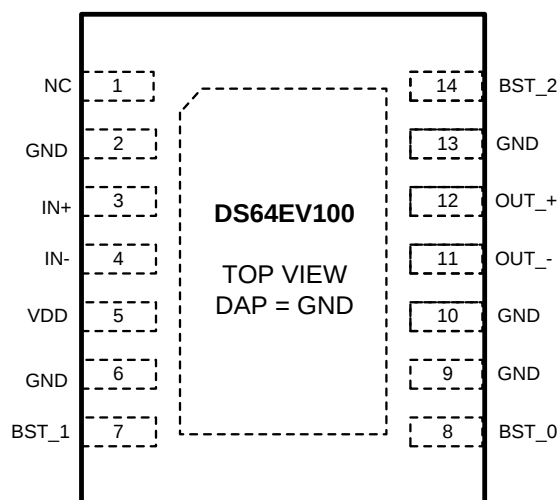


Figure 1. 14-Pin WSON Package
(3 mm x 4 mm x 0.8 mm, 0.5 mm pitch)
See Package Number NHK0014A

Table 1. Pin Descriptions

Pin Name	Pin #	I/O, Type	Description
HIGH SPEED DIFFERENTIAL I/O			
IN+ IN-	3 4	I, CML	Inverting and non-inverting CML differential inputs to the equalizer. An on-chip 100Ω terminating resistor is connected between IN+ and IN-. Refer to Figure 4 .
OUT+ OUT-	12 11	O, CML	Inverting and non-inverting CML differential outputs from the equalizer. An on-chip 50Ω terminating resistor connects OUT+ to V _{DD} and OUT- to V _{DD} .
EQUALIZATION CONTROL			
BST_2 BST_1 BST_0	14 7 8	I, CMOS	BST_2, BST_1, and BST_0 select the equalizer strength. BST_2 is internally pulled high. BST_1 and BST_0 are internally pulled low.
POWER			
V _{DD}	5	I, Power	V _{DD} = 2.5V ±5% or 3.3V ±10%. V _{DD} pins should be tied to V _{DD} plane through low inductance path. A 0.01μF bypass capacitor should be connected between each V _{DD} pin to GND planes.
GND	2, 6, 9, 10, 13	I, Power	Ground reference. GND should be tied to a solid ground plane through a low impedance path.
DAP	PAD	I, Power	Ground reference. The exposed pad at the center of the package must be connected to ground plane of the board.
OTHER			
NC	1		Reserved. Do not connect.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings ⁽¹⁾⁽²⁾

Supply Voltage (V_{DD})	–0.5V to +4V
CMOS Input Voltage	–0.5V to +4.0V
CMOS Output Voltage	–0.5V to +4.0V
CML Input/Output Voltage	–0.5V to +4.0V
Junction Temperature	+150°C
Storage Temperature	–65°C to +150°C
Lead Temperature Soldering, 4 sec	+260°C
ESD Rating	
HBM, 1.5 k Ω , 100 pF	> 8 kV
EIAJ, 0 Ω , 200 pF	> 250 V
Thermal Resistance, θ_{JA} , No Airflow	40 °C/W

- (1) “Absolute Maximum Ratings” indicate limits beyond which damage to the device may occur, including inoperability and degradation of device reliability and/or performance. Functional operation of the device and/or non-degradation at the Absolute Maximum Ratings or other conditions beyond those indicated in the Recommended Operating Conditions is not implied. The Recommended Operating Conditions indicate conditions at which the device is functional and the device should not be operated beyond such conditions. Absolute Maximum Numbers are guaranteed for a junction temperature range of –40°C to +125°C. Models are validated to Maximum Operating Voltages only.
- (2) **If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office / Distributors for availability and specifications.**

Recommended Operating Conditions

	MIN	TYP	MAX	UNIT
Supply Voltage ⁽¹⁾				
$V_{DD2.5}$ to GND	2.375	2.5	2.625	V
$V_{DD3.3}$ to GND	3.0	3.3	3.6	V
Ambient Temperature	–40	25	+85	°C

- (1) The $V_{DD2.5}$ is $V_{DD} = 2.5V \pm 5\%$ and $V_{DD3.3}$ is $V_{DD} = 3.3V \pm 10\%$.

Electrical Characteristics

Over recommended operating supply and temperature ranges unless other specified. ^{(1) (2)}

PARAMETER		TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
POWER						
P	Power Supply Consumption	V _{DD3.3}		140	200	mW
		V _{DD2.5}		100	150	mW
N	Supply Noise Tolerance ⁽³⁾	50 Hz – 100 Hz 100 Hz – 10 MHz 10 MHz – 1.6 GHz		100 40 10		mV _{P-P} mV _{P-P} mV _{P-P}
LVTTTL DC SPECIFICATIONS						
V _{IH}	High Level Input Voltage	V _{DD2.5}	1.6		V _{DD2.5}	V
		V _{IL}	2.0		V _{DD3.3}	V
V _{IL}	Low Level Input Voltage		−0.3		0.8	V
V _{OH}	High Level Input Voltage	I _{OH} = −3 mA, V _{DD3.3}	2.4			V
		I _{IN}	2.0			V
V _{OL}	Low Level Input Voltage	I _{OL} = 3 mA			0.4	V

- (1) Typical values represent most likely parametric norms at $V_{DD} = 3.3V$ or $2.5V$, $T_A = 25^\circ\text{C}$., and at the Recommended Operation Conditions at the time of product characterization and are not guaranteed.
- (2) The Electrical Characteristics tables list guaranteed specifications under the listed Recommended Operating Conditions except as otherwise modified or specified by the Electrical Characteristics Conditions and/or Notes. Typical specifications are estimations only and are not guaranteed.
- (3) Allowed supply noise (mV_{P-P} sine wave) under typical conditions.

Electrical Characteristics (continued)

Over recommended operating supply and temperature ranges unless other specified. ⁽¹⁾ ⁽²⁾

PARAMETER		TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
POWER						
I _{IN}	Input Current	V _{IN} = V _{DD}		+1.8	+15	μA
		V _{IN} = GND	-15	0		μA
I _{IN-P}	Input Leakage Current with Internal Pull-Down/Up Resistors	V _{IN} = GND, with internal pull-down resistors		+95		μA
		V _{IN} = GND, with internal pull-up resistors	-20			μA
CML RECEIVER INPUTS (IN+, IN-)						
V _{TX}	Source Transmit Launch Signal Level (IN diff)	AC-Coupled or DC-Coupled Requirement, Differential measurement at point A. Figure 1	400		1600	mV _{P-P}
V _{INTRE}	Input Threshold Voltage	Differential measurement at point B . Figure 1		120		mV _{P-P}
V _{DDTX}	Supply Voltage of Transmitter to EQ	DC-Coupled Requirement	1.6		V _{DD}	V
V _{ICMDC}	Input Common-Mode Voltage	DC-Coupled Requirement Differential measurement at point A. Figure 1 ⁽⁴⁾	V _{DDTX} ×0.8		V _{DDT} _X ×0.2	V
R _{LI}	Differential Input Return Loss	100 MHz – 3.2 GHz, with fixture's effect de-embedded		10		dB
R _{IN}	Input Resistance	Differential Across IN+ and IN-. Figure 4	85	100	115	Ω
CML OUTPUTS (OUT+, OUT-)						
V _{OD}	Output Differential Voltage Level (OUT diff)	Differential measurement with OUT+ and OUT- terminated by 50Ω to GND, AC-Coupled Figure 2	550	620	725	mV _{P-P}
V _{OCM}	Output Common-Mode Voltage	Single-ended measurement DC-Coupled with 50Ω terminations ⁽⁵⁾	V _{DD} ×0.2		V _{DD} ×0.1	V
t _R , t _F	Transition Time	20% to 80% of differential output voltage, measured within 1" from output pins. Figure 2 ⁽⁵⁾	20		60	ps
R _O	Output Resistance	Single-ended to V _{DD}	42	50	58	Ω
R _{LO}	Differential Output Return Loss	100 MHz – 1.6 GHz, with fixture's effect de-embedded. IN+ = static high.		10		dB
t _{PLHD}	Differential Low to High Propagation Delay	Propagation delay measurement at 50% V _{OD} between input to output, 100 Mbps Figure 3 ⁽⁵⁾		240		ps
t _{PHLD}	Differential High to Low Propagation Delay			240		ps
EQUALIZATION						
DJ1	Residual Deterministic Jitter at 10 Gbps	30" of 6 mil microstrip FR4, EQ Setting 0x06, PRBS-7 (2 ⁷ -1) pattern ⁽⁶⁾⁽⁷⁾		0.20		UI _{P-P}
DJ2	Residual Deterministic Jitter at 6.4 Gbps	40" of 6 mil microstrip FR4, EQ Setting 0x06, PRBS-7 (2 ⁷ -1) pattern ⁽⁶⁾⁽⁷⁾		0.17	0.26	UI _{P-P}
DJ3	Residual Deterministic Jitter at 5 Gbps	40" of 6 mil microstrip FR4, EQ Setting 0x07, PRBS-7 (2 ⁷ -1) pattern ⁽⁶⁾⁽⁷⁾		0.12	0.20	UI _{P-P}
DJ4	Residual Deterministic Jitter at 2.5 Gbps	40" of 6 mil microstrip FR4, EQ Setting 0x07, PRBS-7 (2 ⁷ -1) pattern ⁽⁶⁾⁽⁷⁾		0.10	0.16	UI _{P-P}

(4) Measured with clock-like {11111 00000} pattern.

(5) Measured with clock-like {11111 00000} pattern.

(6) Specification is guaranteed by characterization at optimal boost setting and is not tested in production.

(7) Deterministic jitter is measured at the differential outputs (point C of [Figure 1](#)), minus the deterministic jitter before the test channel (point A of [Figure 1](#)). Random jitter is removed through the use of averaging or similar means.

Electrical Characteristics (continued)

Over recommended operating supply and temperature ranges unless other specified. ⁽¹⁾ ⁽²⁾

PARAMETER	TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
POWER					
RJ	Random Jitter	(5)(8)	0.5		ps _{rms}

(8) Random jitter contributed by the equalizer is defined as $\sqrt{J_{OUT}^2 - J_{IN}^2}$. J_{OUT} is the random jitter at equalizer outputs in ps_{rms}, see point C of Figure 1; J_{IN} is the random jitter at the input of the equalizer in ps_{rms}, see Figure 1.

TIMING DIAGRAMS

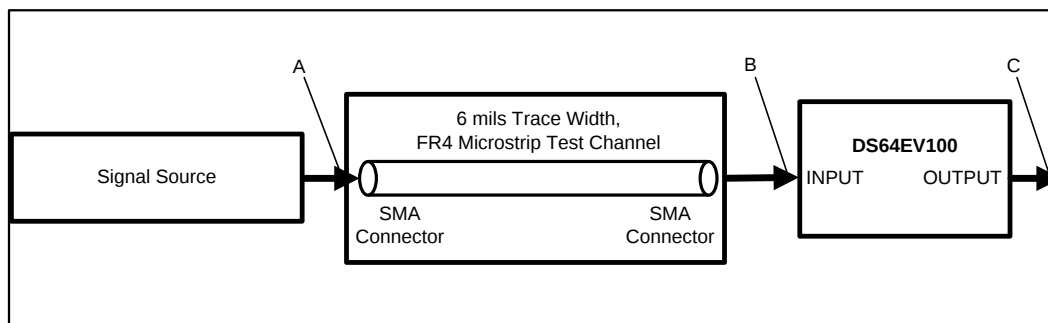


Figure 2. Test Setup Diagram

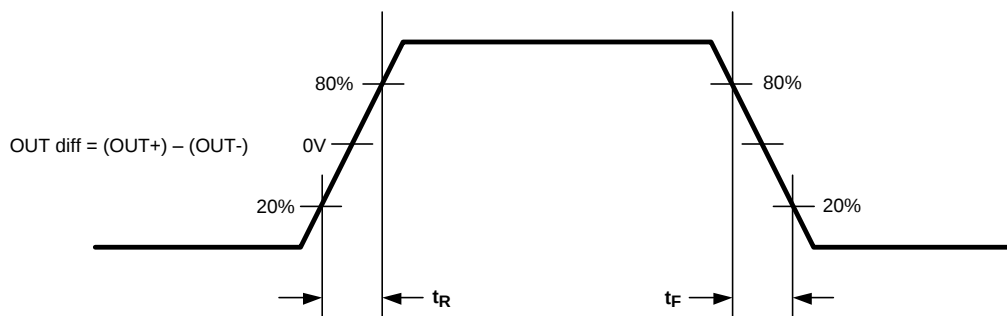


Figure 3. CML Output Transition Times

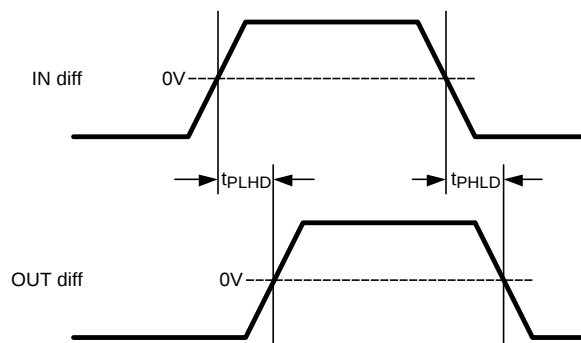


Figure 4. Propagation Delay Timing Diagram

TIMING DIAGRAMS (continued)

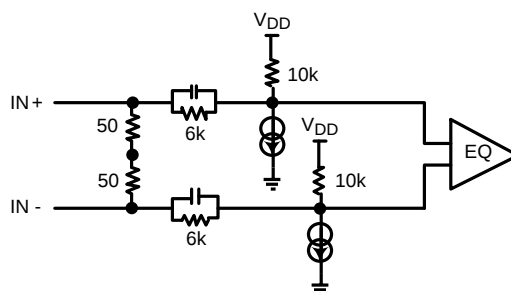


Figure 5. Simplified Receiver Input Termination Circuit

DS64EV100 APPLICATIONS INFORMATION

The DS64EV100 is a programmable equalizer optimized for operation up to 10 Gbps for backplane and cable applications. The equalizer channel consists of an equalizer stage, a limiting amplifier, a DC offset correction block, and a CML driver as shown in Figure 6.

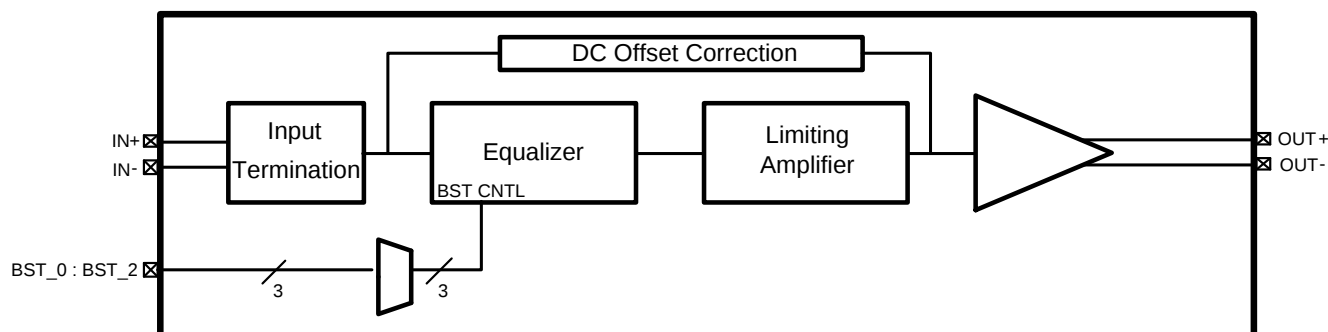


Figure 6. Simplified Block Diagram

EQUALIZER BOOST CONTROL

The equalizer channel supports eight programmable levels of equalization boost, and is controlled by the Boost Set pins (BST_[2:0]) in accordance with Table 2. The eight levels of boost settings enables the DS64EV100 to address a wide range of media loss and data rates.

Table 2. EQ Boost Control Table

6 mil Microstrip FR4 Trace Length (in)	24 AWG Twin-AX Cable Length (m)	Channel Loss at 3.2 GHz (dB)	Channel Loss at 5 GHz (dB)	BST_N [2, 1, 0]
0	0	0	0	0 0 0
5	2	5	6	0 0 1
10	3	7.5	10	0 1 0
15	4	10	14	0 1 1
20	5	12.5	18	1 0 0 (Default)
25	6	15	21	1 0 1
30	7	17	24	1 1 0
40	10	22	30	1 1 1

GENERAL RECOMMENDATIONS

The DS64EV100 is a high performance circuit capable of delivering excellent performance. Careful attention must be paid to the details associated with high-speed design as well as providing a clean power supply. Refer to the LVDS Owner's Manual for more detailed information on high-speed design tips to address signal integrity design issues.

PCB LAYOUT CONSIDERATIONS FOR DIFFERENTIAL PAIRS

The CML inputs and outputs must have a controlled differential impedance of 100Ω. It is preferable to route CML lines exclusively on one layer of the board, particularly for the input traces. The use of vias should be avoided if possible. If vias must be used, they should be used sparingly and must be placed symmetrically for each side of a given differential pair. Route the CML signals away from other signals and noise sources on the printed circuit board. See AN-1187 for additional information on WSON packages.

POWER SUPPLY BYPASSING

Two approaches are recommended to ensure that the DS64EV100 is provided with an adequate power supply. First, the supply (V_{DD}) and ground (GND) pins should be connected to power planes routed on adjacent layers of the printed circuit board. The layer thickness of the dielectric should be minimized so that the V_{DD} and GND planes create a low inductance supply with distributed capacitance. Second, careful attention to supply bypassing through the proper use of bypass capacitors is required. A 0.01μF bypass capacitor should be connected to each V_{DD} pin such that the capacitor is placed as close as possible to the DS64EV100. Smaller body size capacitors can help facilitate proper component placement. Additionally, three capacitors with capacitance in the range of 2.2 μF to 10 μF should be incorporated in the power supply bypassing design as well. These capacitors can be either tantalum or an ultra-low ESR ceramic and should be placed as close as possible to the DS64EV100.

DC COUPLING

The DS64EV100 supports both AC coupling with external ac coupling capacitor, and DC coupling to its upstream driver, or downstream receiver. With DC coupling, users must ensure the input signal common mode is within the range of the electrical specification V_{ICMDC} and the device output is terminated with 50 Ω to V_{DD} .

TYPICAL PERFORMANCE EYE DIAGRAMS AND CURVES

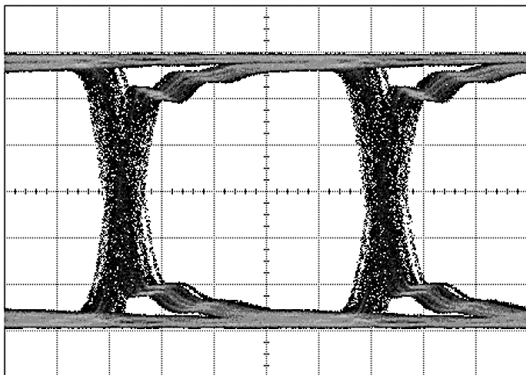


Figure 7. Equalized Signal
(40 in FR4, 2.5 Gbps, PRBS7, 0x07 Setting)

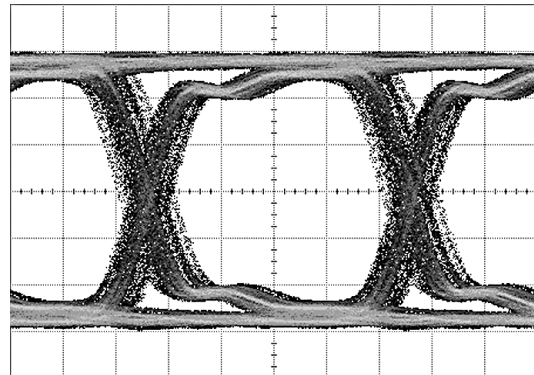


Figure 8. Equalized Signal
(40 in FR4, 5 Gbps, PRBS7, 0x07 Setting)

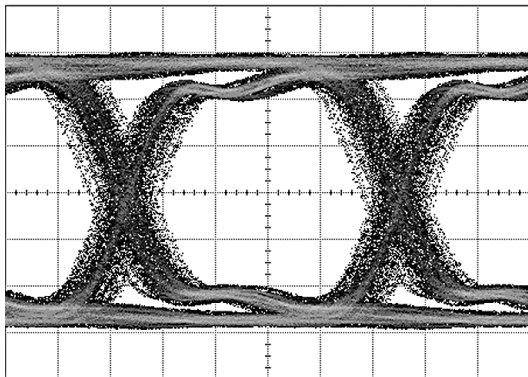


Figure 9. Equalized Signal
(40 in FR4, 6.4 Gbps, PRBS7, 0x06 Setting)

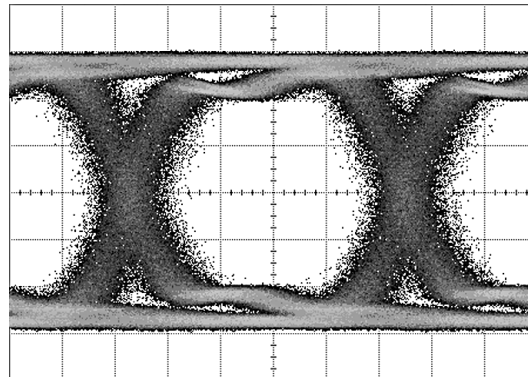


Figure 10. Equalized Signal
(40 in FR4, 6.4 Gbps, PRBS31, 0x06 Setting)

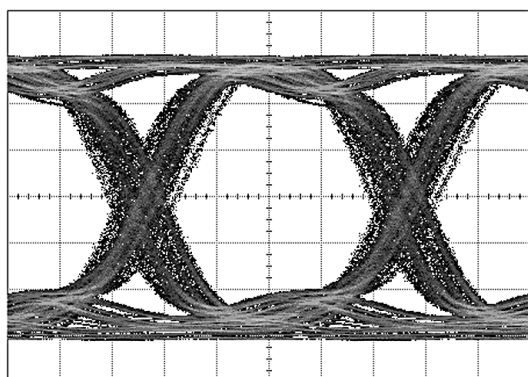


Figure 11. Equalized Signal
(30 in FR4, 10 Gbps, PRBS7, 0x06 Setting)

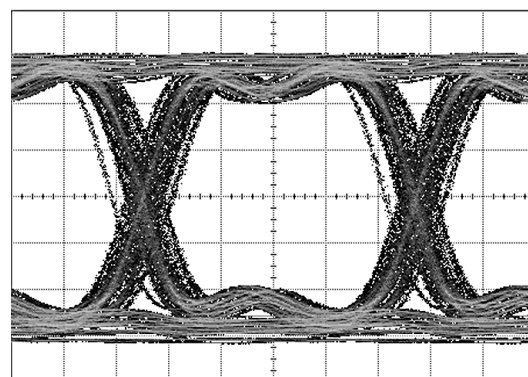


Figure 12. Equalized Signal
(10m 24 AWG Twin-AX Cable, 6.4 Gbps, PRBS7, 0x06 Setting)

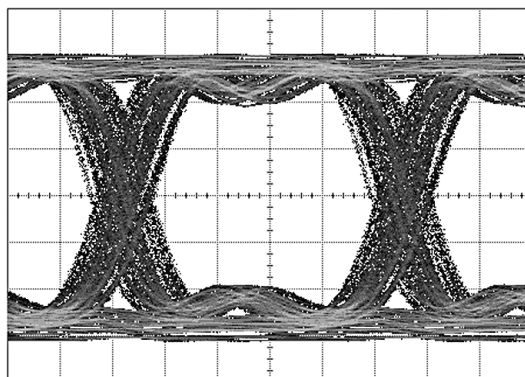


Figure 13. Equalized Signal
(32 in Tyco XAUI Backplane, 6.25 Gbps, PRBS7, 0x06 Setting)

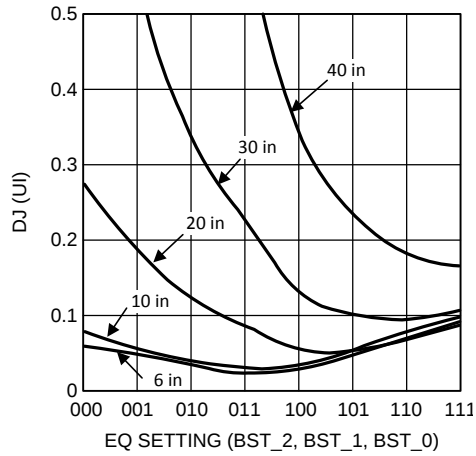


Figure 14. DJ vs. EQ Setting (6.4 Gbps)

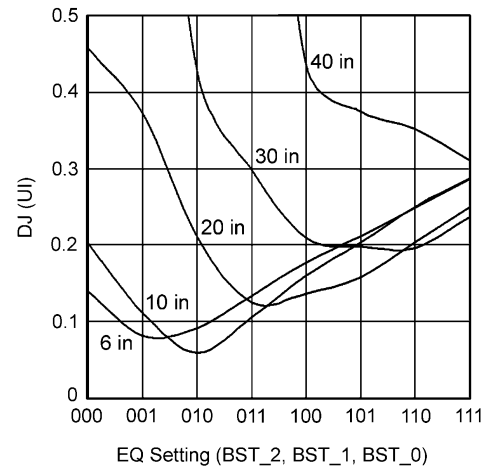


Figure 15. DJ vs. EQ Setting (10 Gbps)

REVISION HISTORY

Changes from Revision D (February 2013) to Revision E

Page

- Changed layout of National Data Sheet to TI format [9](#)

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
DS64EV100SD/NOPB	ACTIVE	WSON	NHK	14	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	D64E1SD	Samples
DS64EV100SDX/NOPB	ACTIVE	WSON	NHK	14	4500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	D64E1SD	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

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TAPE AND REEL INFORMATION


*All dimensions are nominal

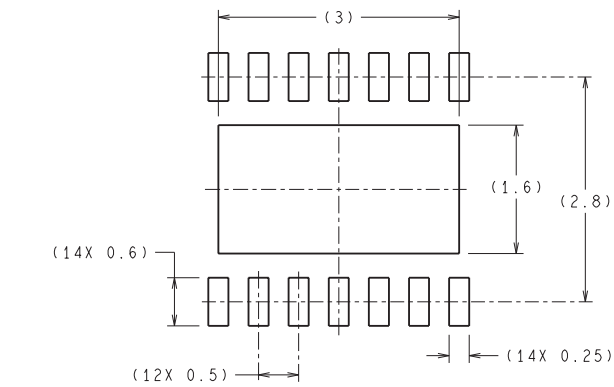
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
DS64EV100SD/NOPB	WSO	NHK	14	1000	178.0	12.4	3.3	4.3	1.0	8.0	12.0	Q1
DS64EV100SDX/NOPB	WSO	NHK	14	4500	330.0	12.4	3.3	4.3	1.0	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

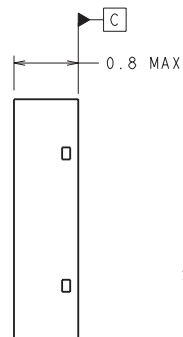
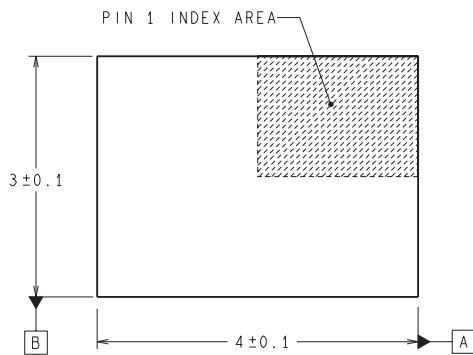


*All dimensions are nominal

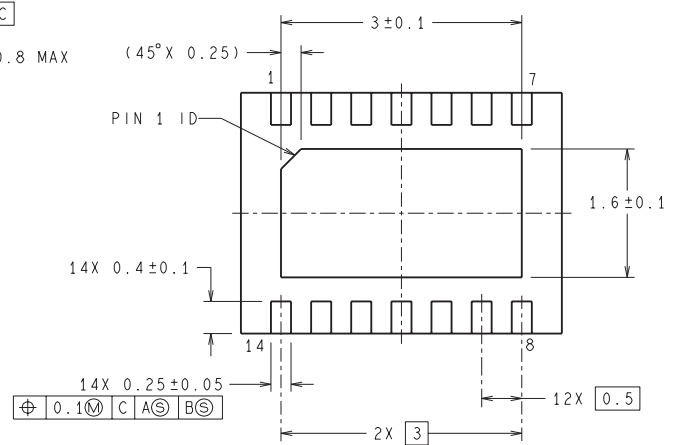
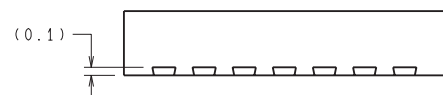
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
DS64EV100SD/NOPB	WSON	NHK	14	1000	210.0	185.0	35.0
DS64EV100SDX/NOPB	WSON	NHK	14	4500	367.0	367.0	35.0



RECOMMENDED LAND PATTERN



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SDA14A (Rev A)

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Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

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